

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	30	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 4) V _{GS} = 4.0V	Steady State	T _A = 25°C T _A = 70°C	I _D	0.27 0.21	A
Continuous Drain Current (Note 5) V _{GS} = 4.0V	Steady State	T _A = 25°C T _A = 70°C	I _D	0.31 0.25	A
Continuous Drain Current (Note 5) V _{GS} = 4.0V	t ≤ 10s	T _A = 25°C T _A = 70°C	I _D	0.38 0.3	A
Continuous Drain Current (Note 4) V _{GS} = 2.5V	Steady State	T _A = 25°C T _A = 70°C	I _D	0.21 0.15	A
Continuous Drain Current (Note 5) V _{GS} = 2.5V	t ≤ 10s	T _A = 25°C T _A = 70°C	I _D	0.29 0.22	A
Pulsed Drain Current (Note 6)			I _{DM}	1.2	A

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 4)	P _D	0.28	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 4)	R _{θJA}	474	°C/W
Power Dissipation (Note 5)	P _D	0.36	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 5)	R _{θJA}	361	°C/W
Power Dissipation (Note 5) t ≤ 10s	P _D	0.52	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 5) t ≤ 10s	R _{θJA}	252	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @ T_A = 25°C unless otherwise stated

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	0.1	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±1.0	μA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	0.5	-	1.5	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	1.3	2	Ω	V _{GS} = 4V, I _D = 10mA
		-	1.6	3.2		V _{GS} = 2.5V, I _D = 1mA
Forward Transfer Admittance	Y _{fs}	-	93	-	mS	V _{DS} = 3V, I _D = 10mA
Diode Forward Voltage	V _{SD}	-	0.7	1.3	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	-	36.3	-	pF	V _{DS} = 5V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	7.6	-		
Reverse Transfer Capacitance	C _{rss}	-	4.7	-		
Gate Resistance	R _g	-	128	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	-	0.5	-	nC	V _{GS} = 4.5V, V _{DS} = 15V, I _D = 10mA
Gate-Source Charge	Q _{gs}	-	0.1	-		
Gate-Drain Charge	Q _{gd}	-	0.1	-		
Turn-On Delay Time	t _{D(on)}	-	4.5	-	ns	V _{GS} = 4.5V, V _{DS} = 15V, R _G = 2Ω, I _D = 180mA
Turn-On Rise Time	t _r	-	2.24	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	19.2	-	ns	
Turn-Off Fall Time	t _f	-	28.2	-	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
 - Device mounted on 2" x 2" FR-4 PCB with high coverage 2 oz. Copper, single sided.
 - Repetitive rating, pulse width limited by junction temperature.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

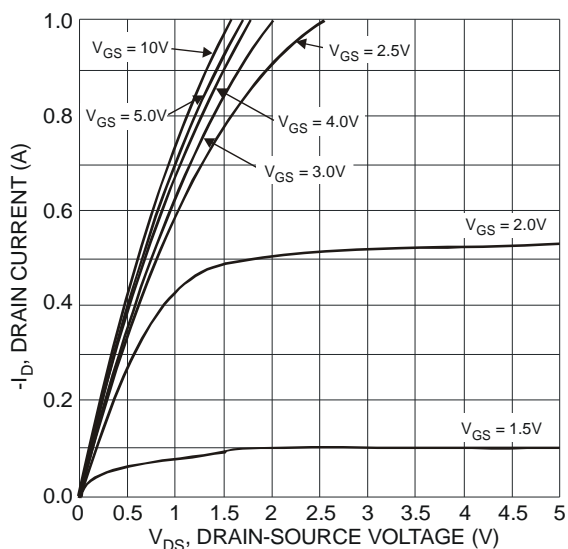


Fig. 1 Typical Output Characteristics

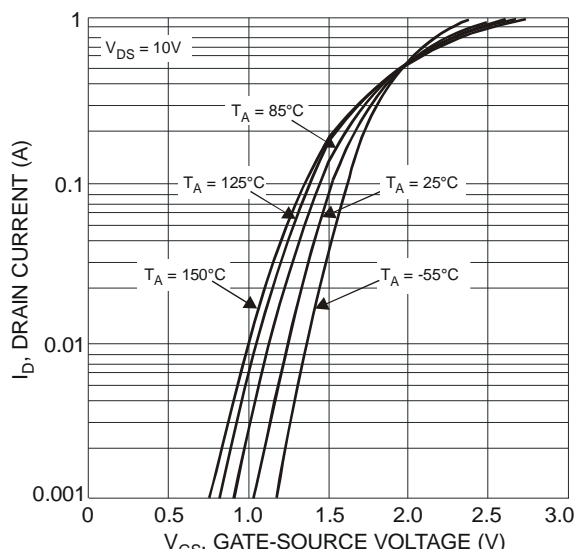


Fig. 2 Typical Transfer Characteristics

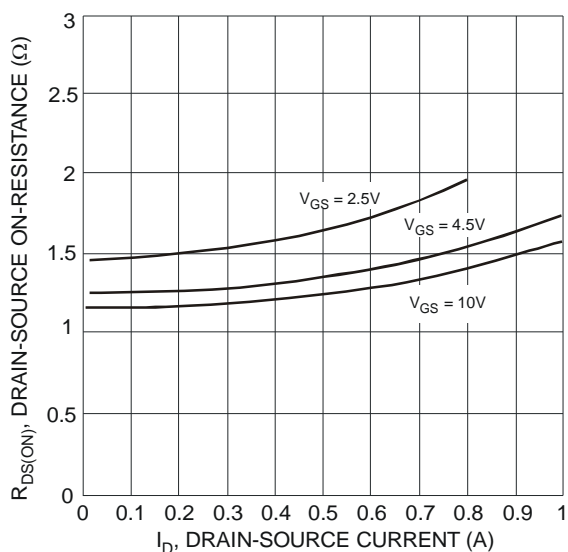


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

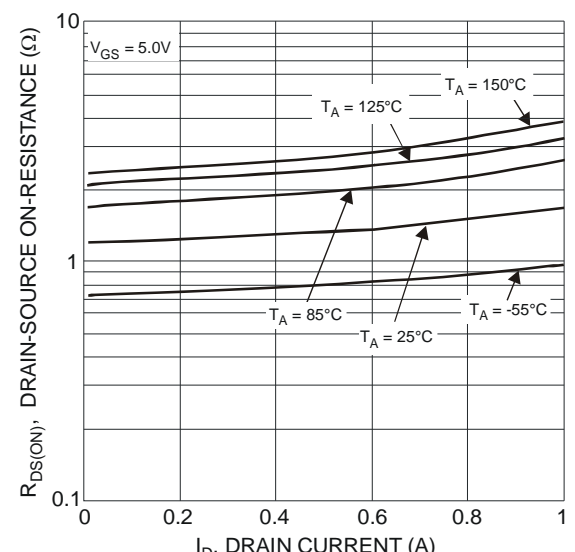


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

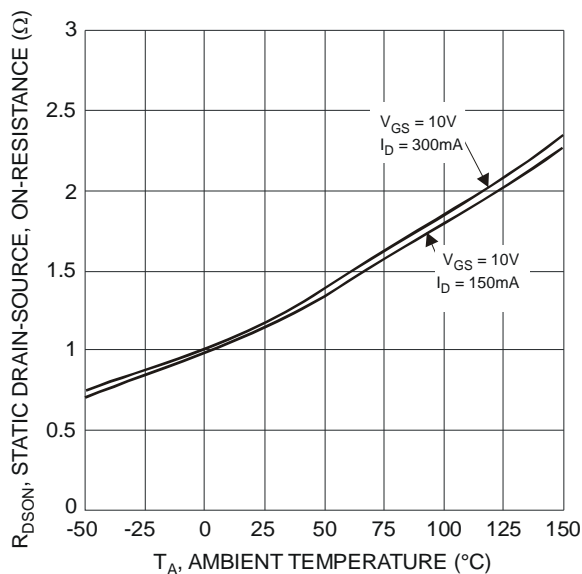


Fig. 5 On-Resistance Variation with Temperature

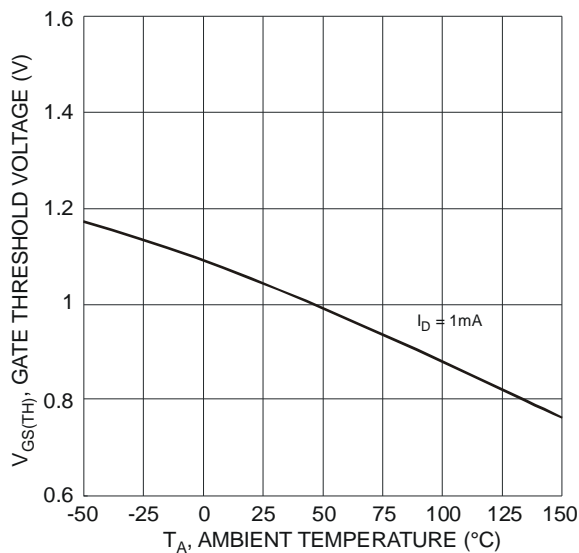
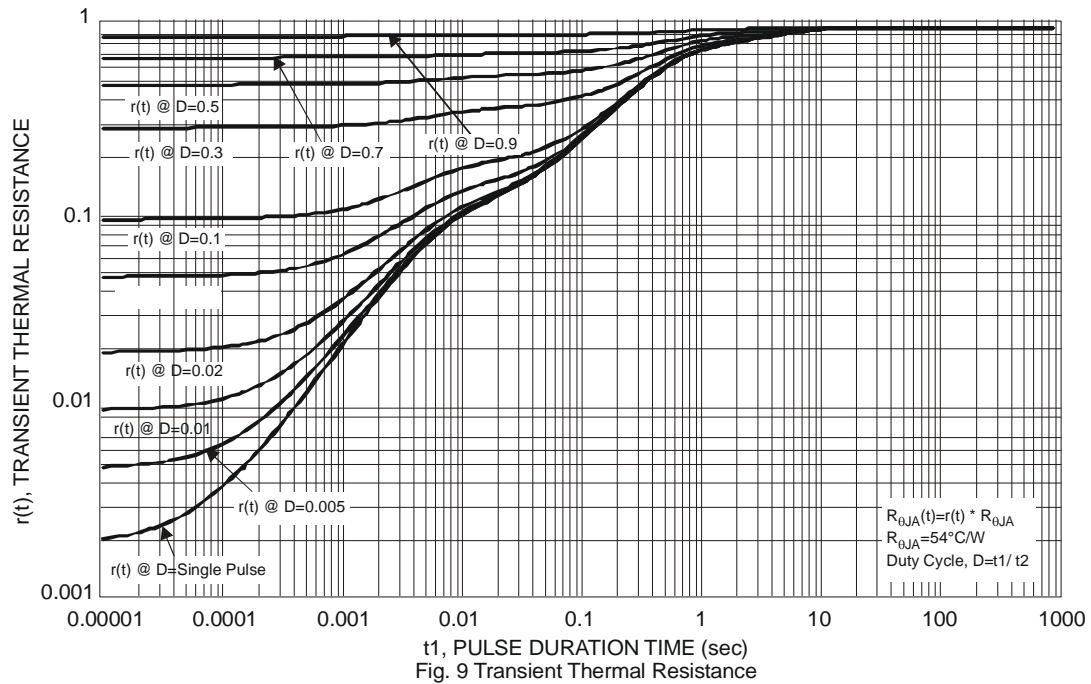
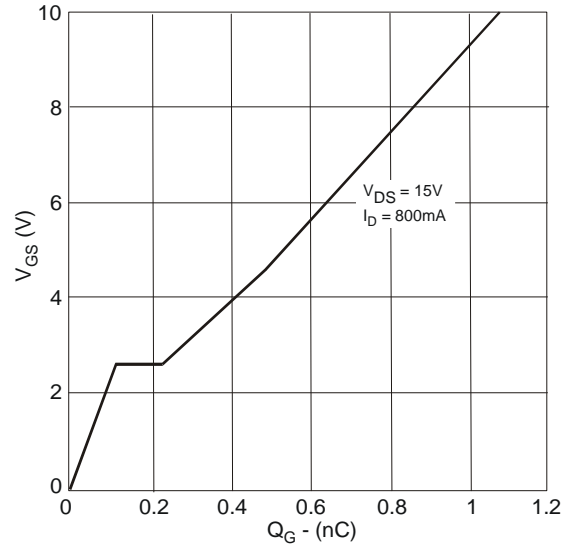
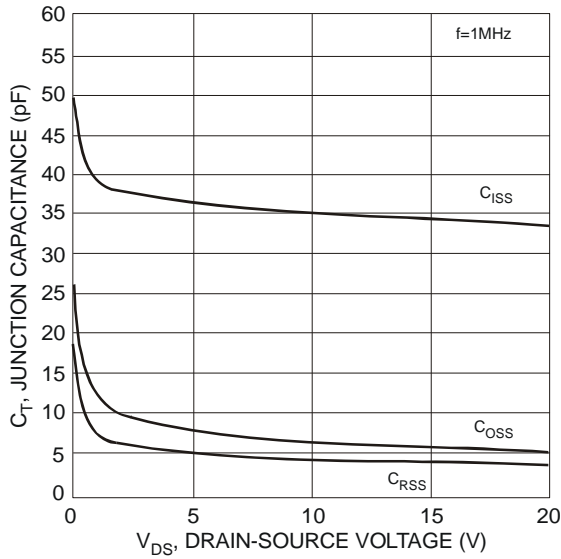
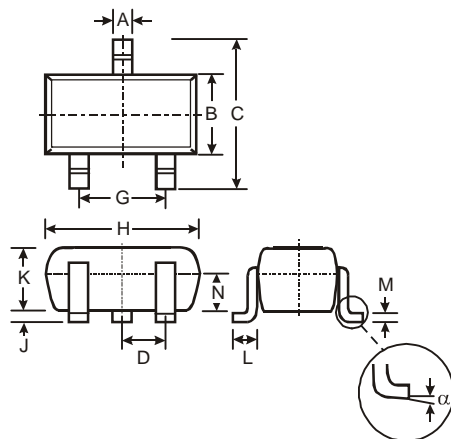


Fig. 6 Gate Threshold Variation vs. Ambient Temperature

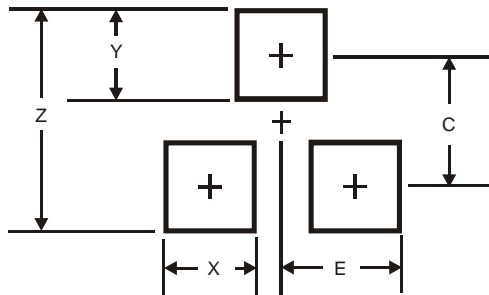


Package Outline Dimensions



SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7

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